

# Air Cooling Research and Development



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**National Renewable Energy Laboratory**  
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**Project ID #: APE019**

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# State of the Art

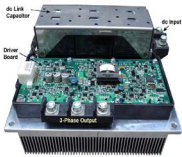
Everything on a vehicle is **air cooled**,  
*ultimately...*

**Intermediate** liquid cooling loop



[1]

Air cooling can be done... When?... How?



[2,3]

**Honda Insight**

Power Rating 12 kW



[4,5]

**AC Propulsion AC-150**

Power Rating 150 kW

# **Relevance:**

## **Challenges/Barriers to Meet Project Goals**

**Goal: Develop air-cooled thermal management system solutions that help meet DOE's 2015 technical targets on time**

### Challenges

- **Air is a poor heat-transfer fluid**
  - low specific heat
  - low density
  - low conductivity
- **Parasitic power**
- **Novelty for this application**

### Advantages

- **Everything on a vehicle is ultimately air cooled**
- **Rejecting heat to air can eliminate intermediate liquid loops**
- **Air is benign and need not be carried**
- **Air is a dielectric and can contact the chip directly**
- **Enables high temperature devices**

### FY13 Project-Specific Goals

- **Demonstrate promising FY12 feasibility analysis at the module level with optimized design by testing with simulated electric device heat generation**
- **Conduct detailed analysis at system level to show progress relative to DOE technical targets**

# Overview

## Timeline

Phase II start date: FY10

Project end date: FY15

Phase II complete: 50%

## Budget

**Total Project Phase II Funding:**

DOE Share: \$1,700K

**Funding Received in FY12:** \$600K

**Funding for FY13:** \$500K

## Barriers

- **Cost** – Eliminate need for secondary liquid coolant loop and associated cost and complexity
- **Weight** – Reduce unnecessary coolant, coolant lines, pump and heat exchangers for lower system-level weight
- **Performance** – Maintain temperatures in acceptable range while reducing complexity and system-level parasitic losses

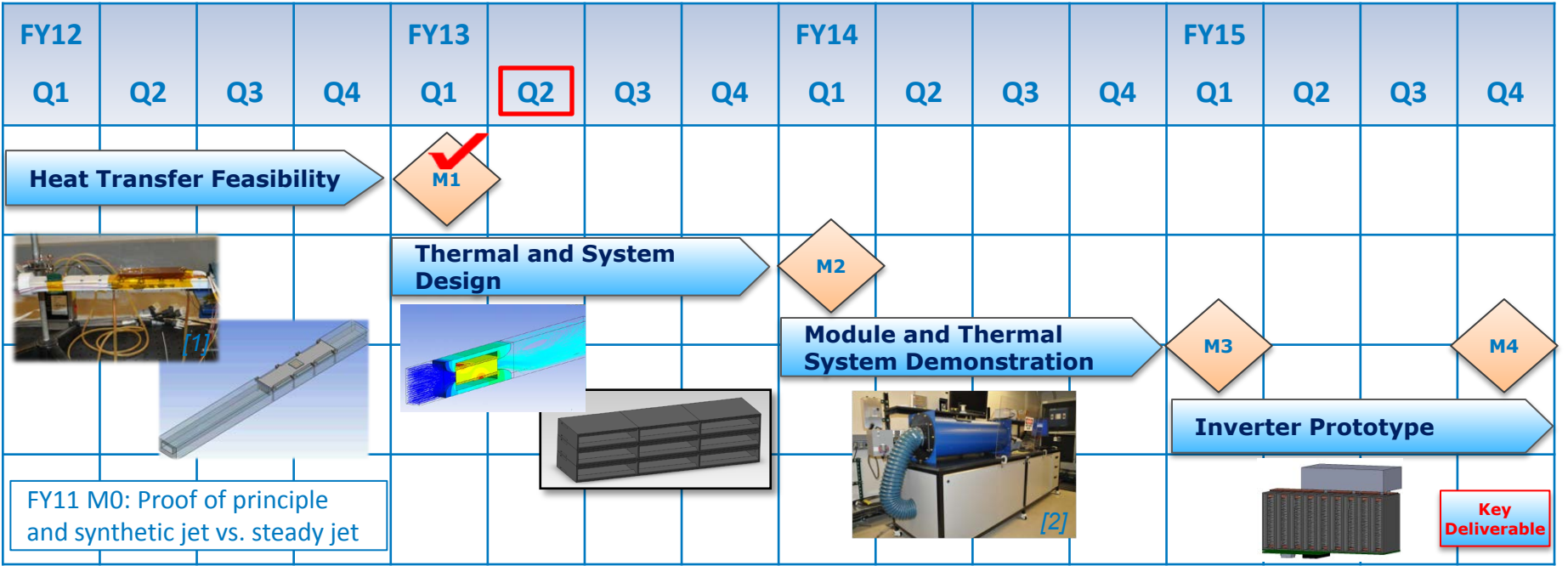
**Vehicle Technologies Program 2015 Targets**

**12 kW/L, 12 kW/kg, \$5/kW**

## Partners

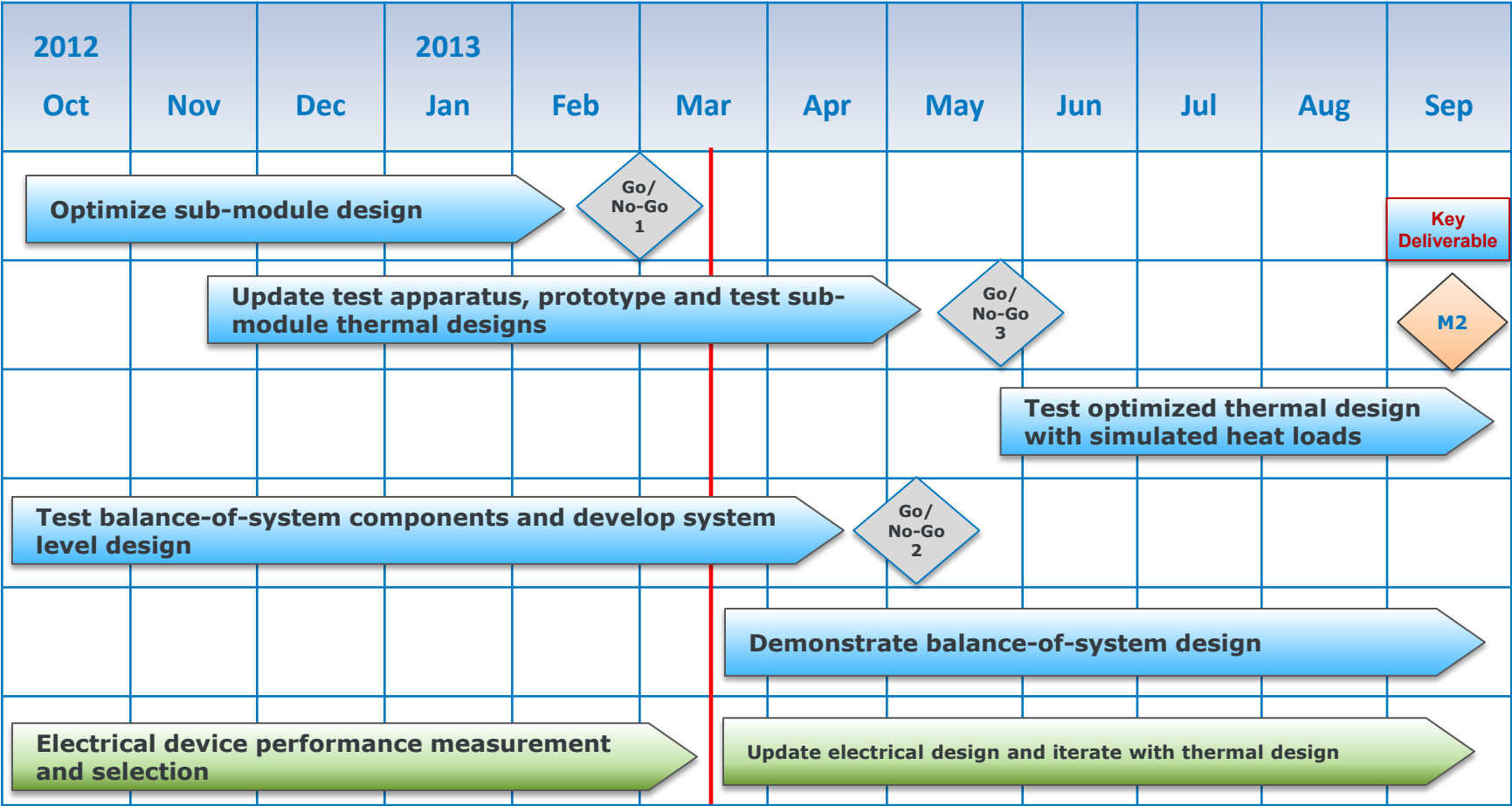
- Oak Ridge National Laboratory (ORNL)
  - Madhu Chinthavali
  - Andrew Wereszczak
- Sapa, GE, and Momenive Performance Materials

# Project Summary: FY11 – FY15 Milestones



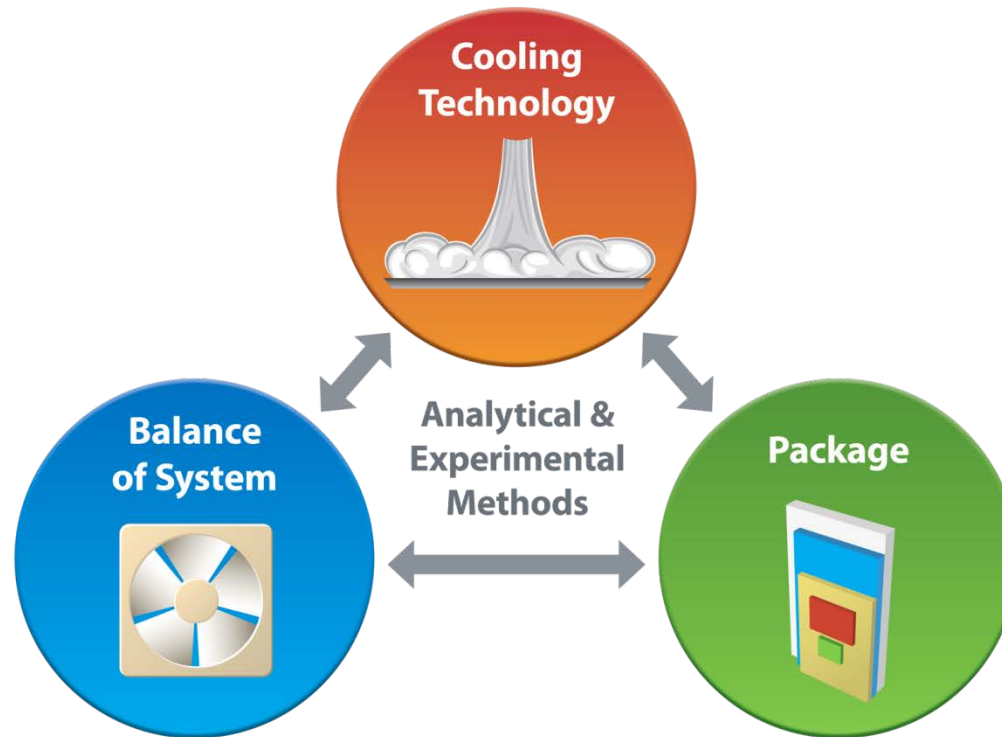
Deliverable/Milestone	Go/No Go
M1 (NREL): Heat transfer feasibility study M1 (ORNL): Device level evaluation	Heat transfer accomplished with reasonable flow and pressure loss? <span>✓</span>
M2: Build and test thermal module and initial balance-of-system M2: Module electrical design	Demonstrated design on track to meet targets?
M3: Demonstrate operating module and inverter thermal system M3: Electrical inverter design and module build	Met targets for module level? Pursue full inverter prototype build?
M4: Improve and prototype full inverter thermal system M4: Full inverter prototype build	Met 2015 targets with 55 kW inverter? Pursue concept further with industry partners?

# FY13 Tasks to Achieve Key Deliverable



- Go/No-Go 1: Optimized design is on track to meet thermal requirements? ✓
- Go/No-Go 2: Balance-of-system design on track to meet air flow requirements?
- Go/No-Go 3: Module thermal design on track and complete?
- Key Deliverable, M2: Demonstrate feasibility of high temperature air cooled module, determine feasibility for meeting program goals

# Strategy: System Approach



## Thermal Environment

- Inverter Location
- Air Source

## Device Type

- Max Temperature
- Efficiency

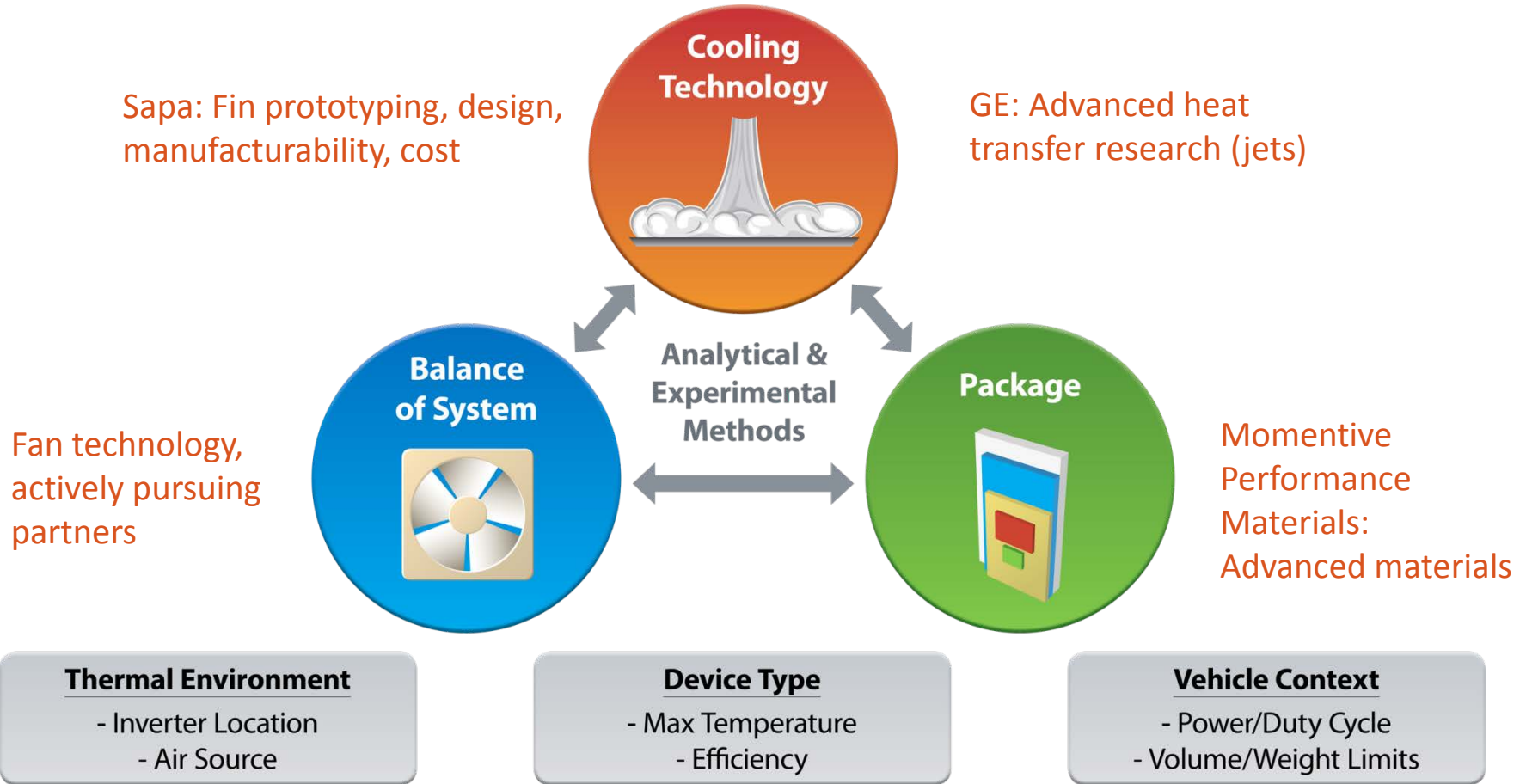
## Vehicle Context

- Power/Duty Cycle
- Volume/Weight Limits



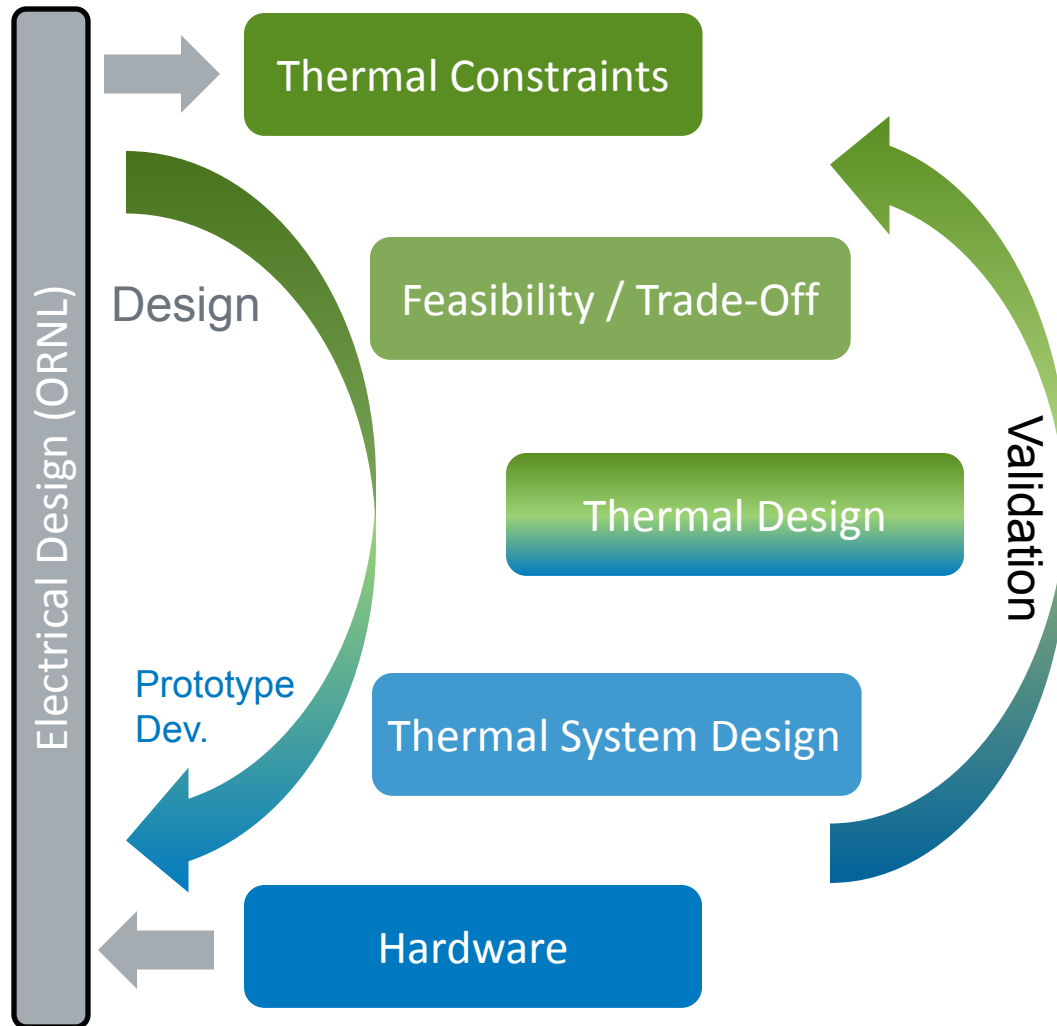
# Strategy: System Approach – Partners

ORNL: Advanced device technology, electrical topology, and full system design



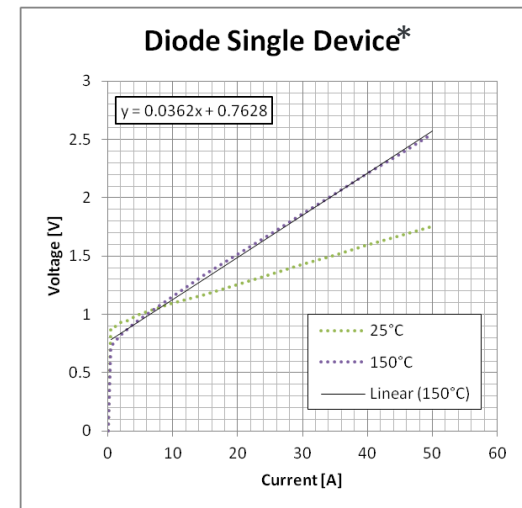


# High Temperature Air-Cooled Inverter



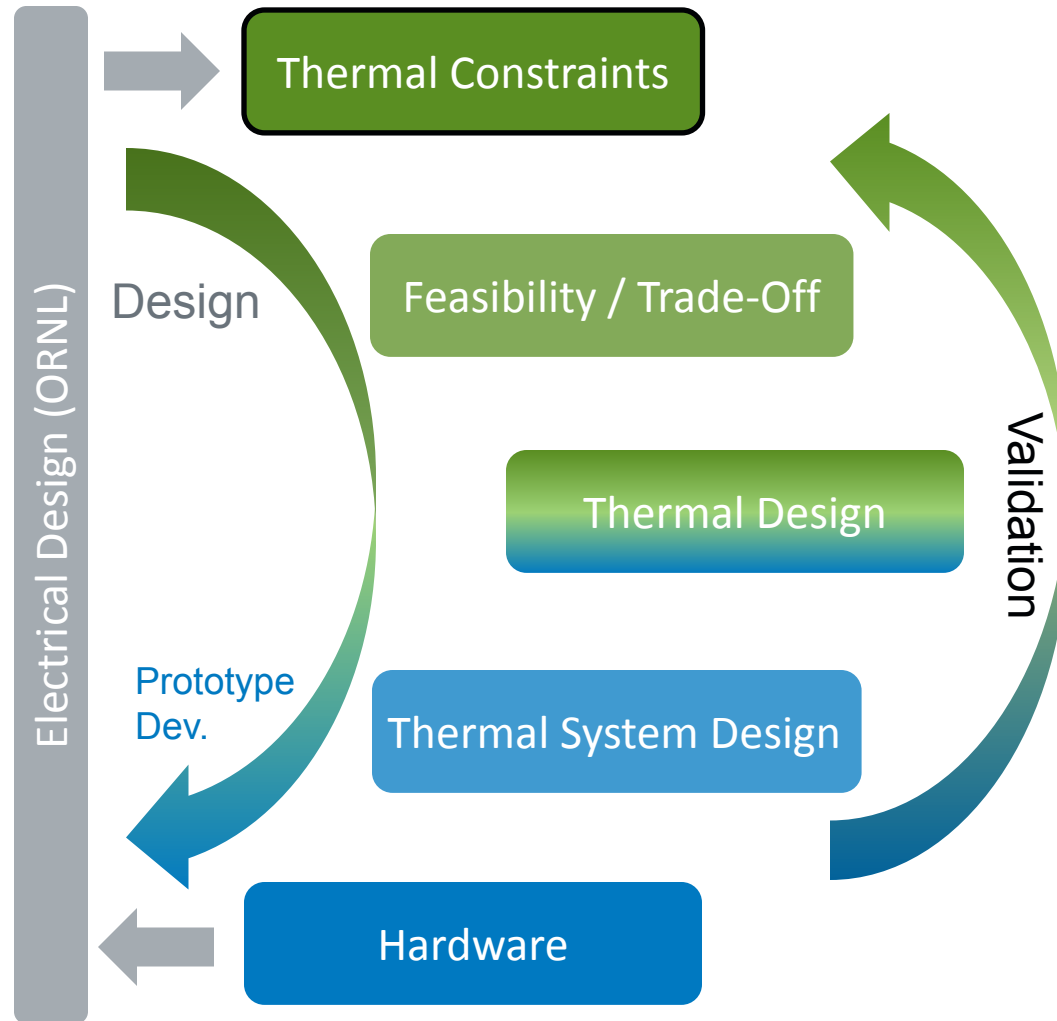
## Electrical Design

- Device type
- Device locations
- Electrical duty cycles
- Temperature-dependent loss equations
- Inverter efficiency



\*Chinthavali, M. "Wide Bandgap Materials." Section 2.1. DOE 2010 Annual Progress Report for Advanced Power Electronics and Electric Motors. Susan A. Rogers. January 2011.

# High Temperature Air-Cooled Inverter



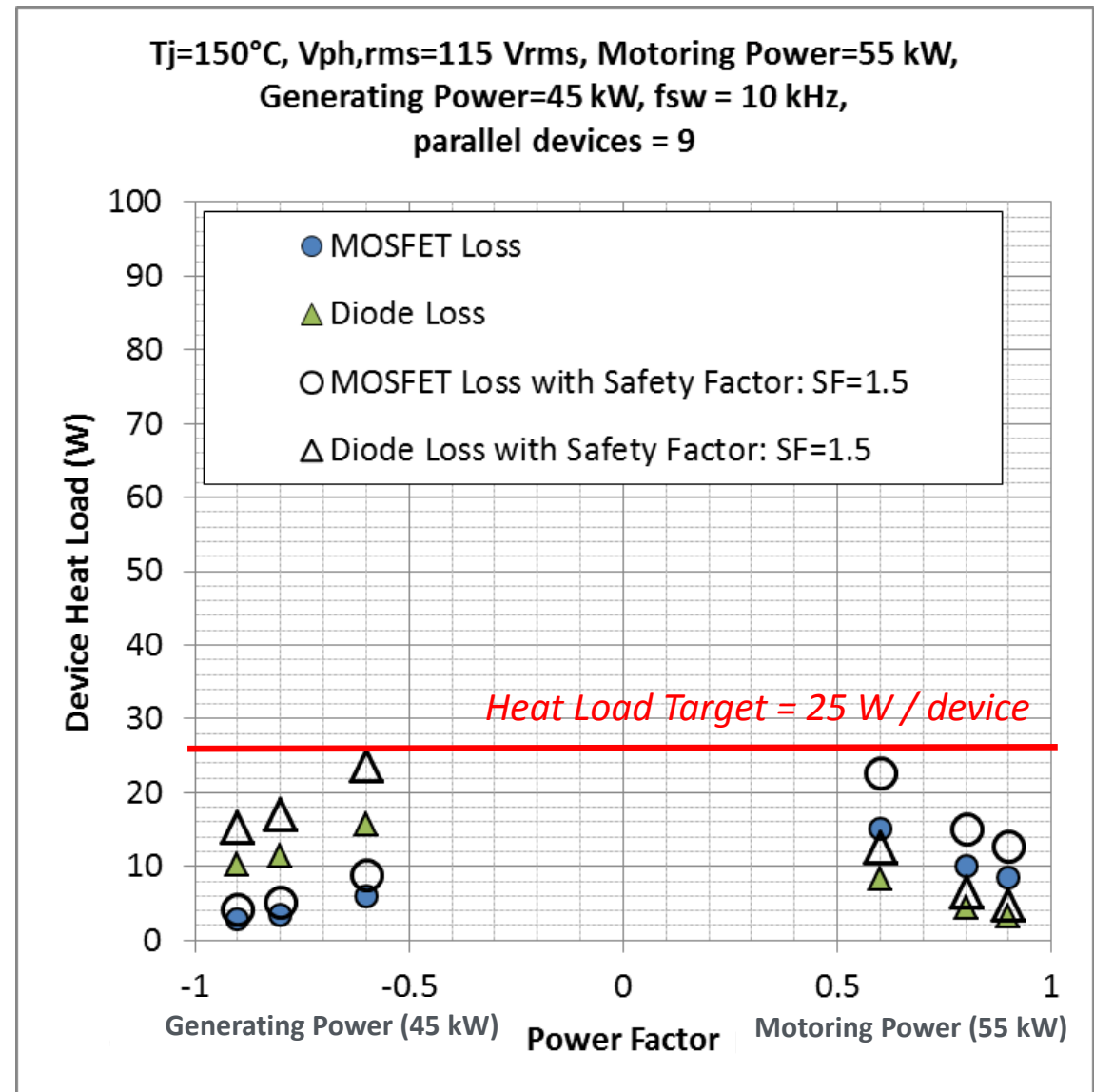
## Thermal Constraints

- **Maximum junction temperature**
- **Heat generation**
  - Efficiency estimate
  - Analytical method
  - Switching model
- **Coolant temperature**

# Heat Generation: 9 parallel devices

*Target 2.7 kW heat, 95% efficient at 55 kW electrical*

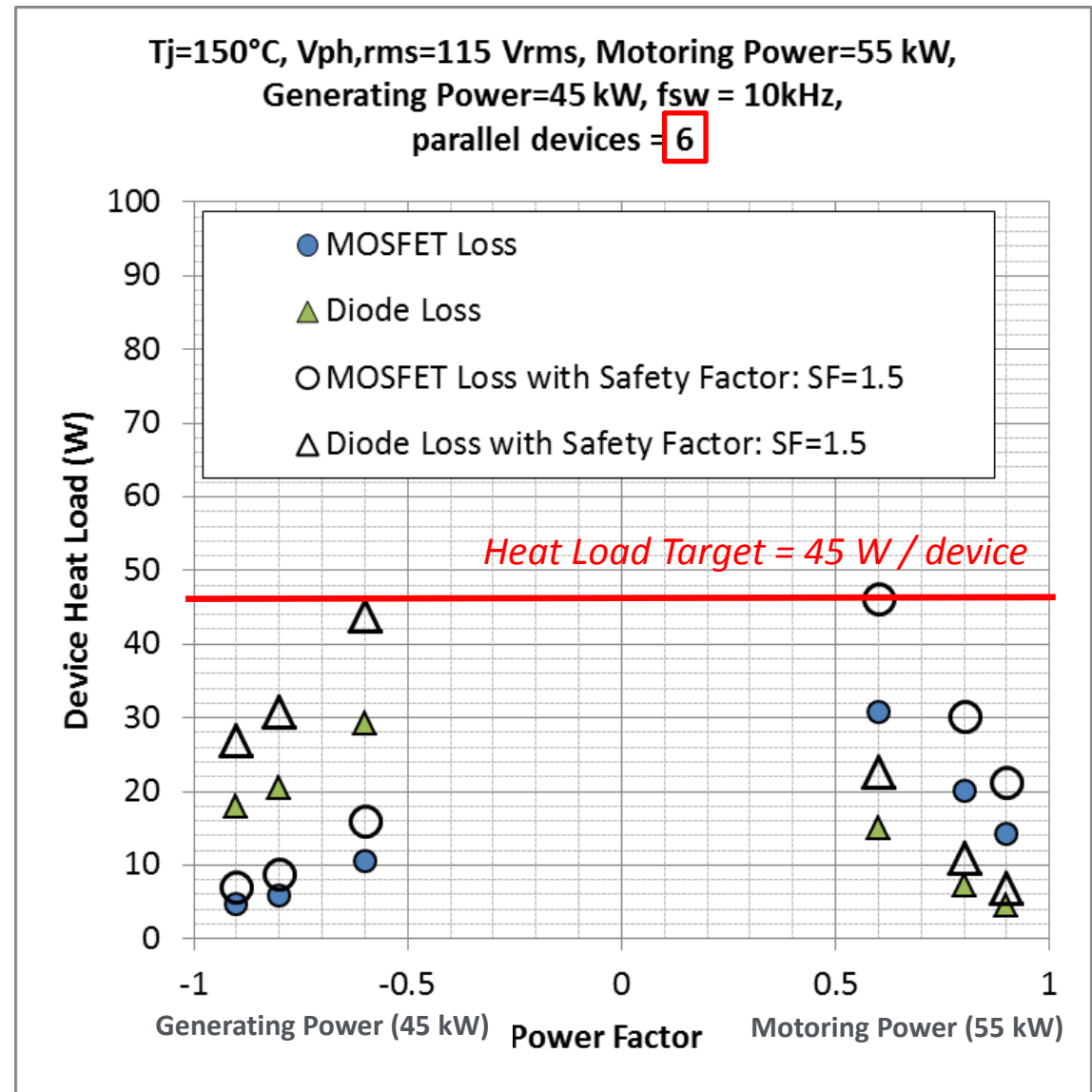
- Device data from ORNL
- Standard analytical equations
- Heat loads will vary with operating conditions
  - Conservative current operation condition
  - Conservative power factor
- Applied 1.5 safety factor to MOSFET heat loss for heat load target
- Used heat load target for all devices



# Heat Generation: 6 Parallel Devices

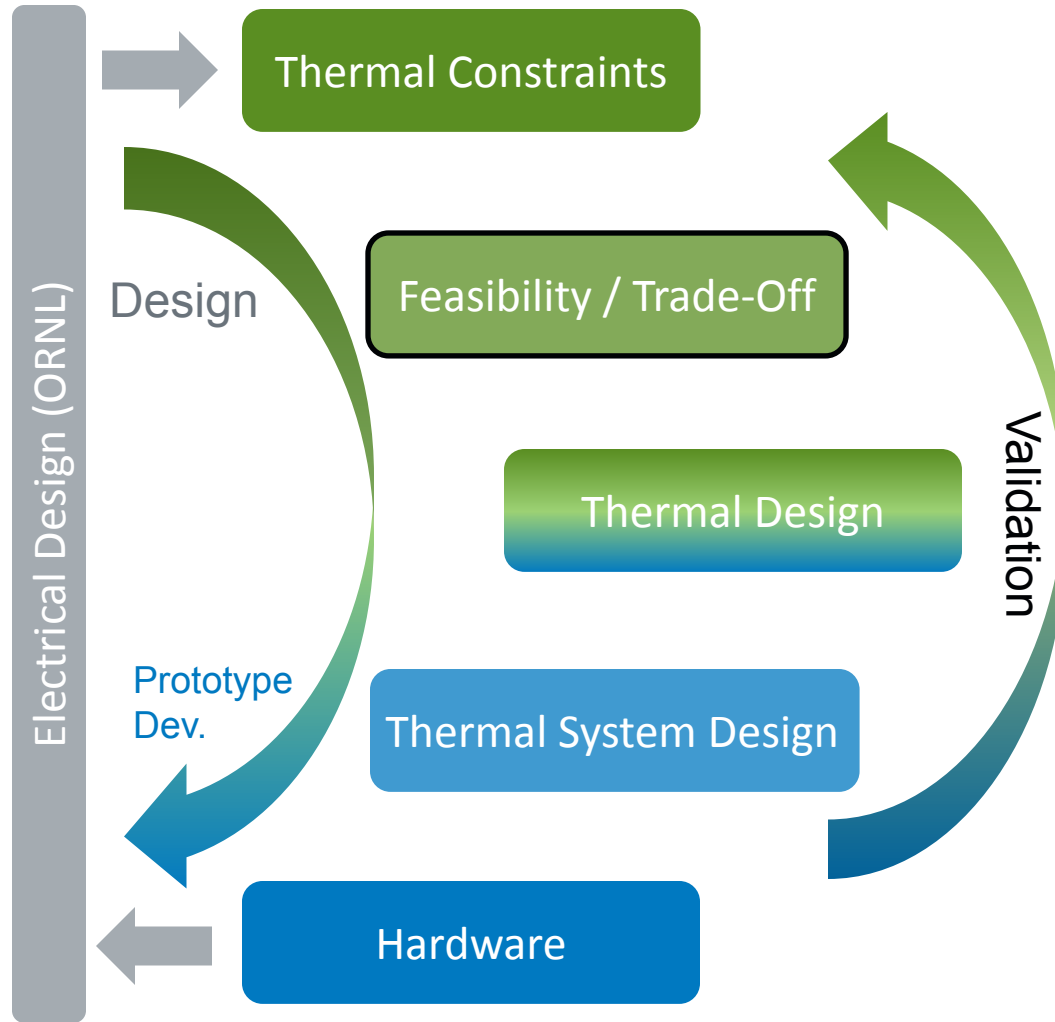
*Target 3.24 kW heat, 94% efficient at 55 kW electrical*

- Device data from ORNL
- Standard analytical equations
- Heat loads will vary with operating conditions
  - Conservative current operation condition
  - Conservative power factor
- Applied 1.5 safety factor to MOSFET heat loss for heat load target
- Used heat load target for all devices



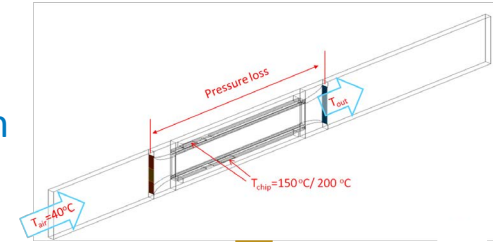
# High Temperature Air-Cooled Inverter

FY12/Milestone 1

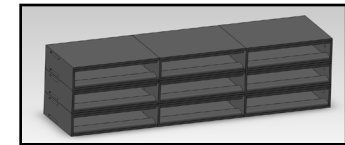


## Feasibility/Trade-off

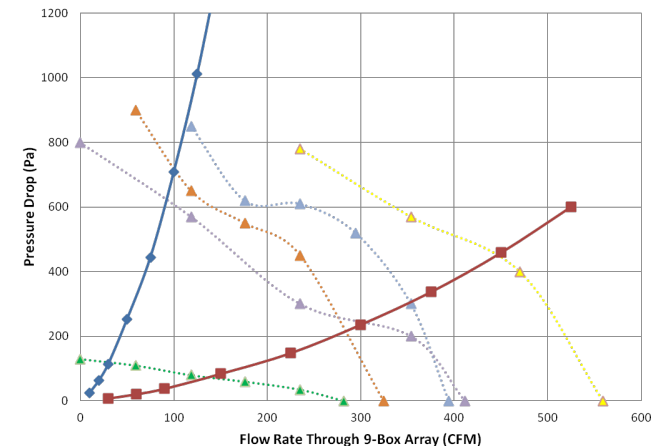
Single Fin  
CFD



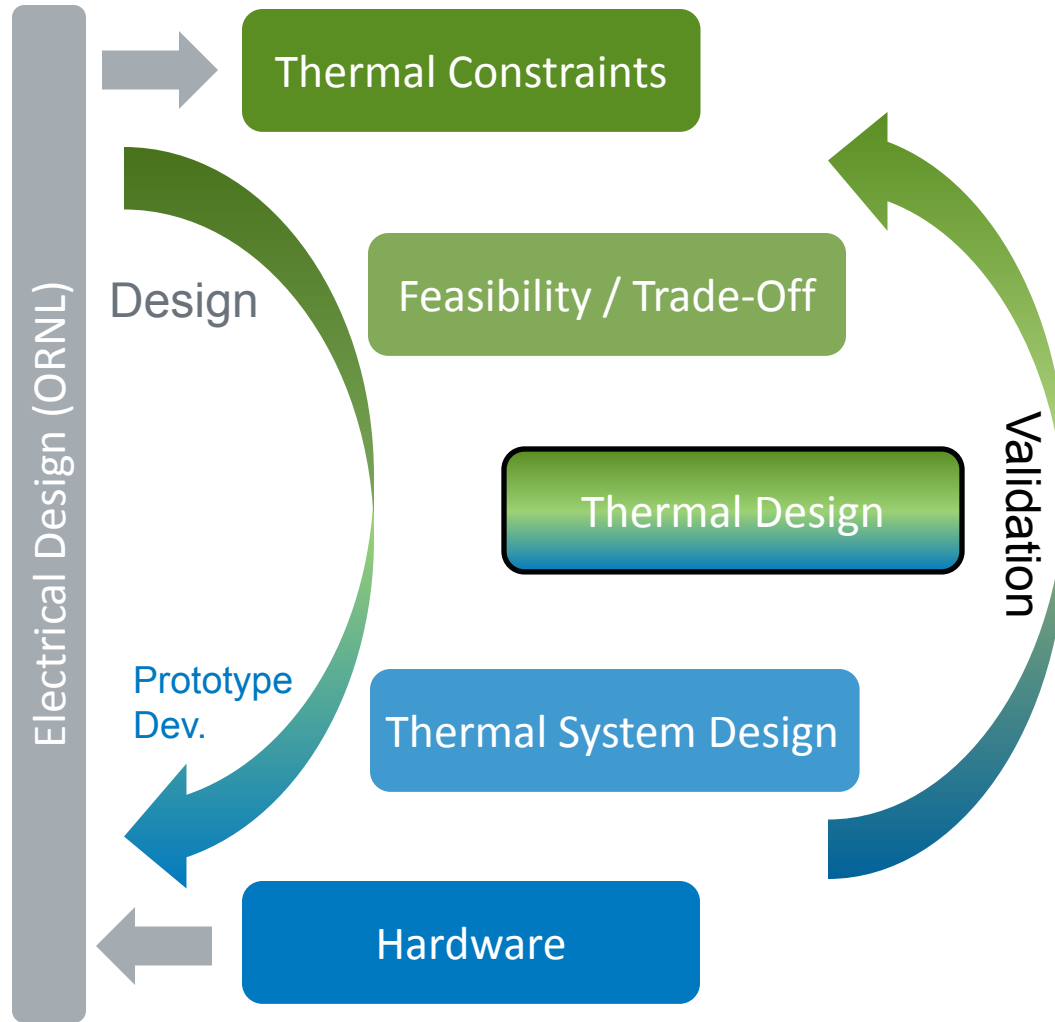
Extrapolate  
system



Add fan

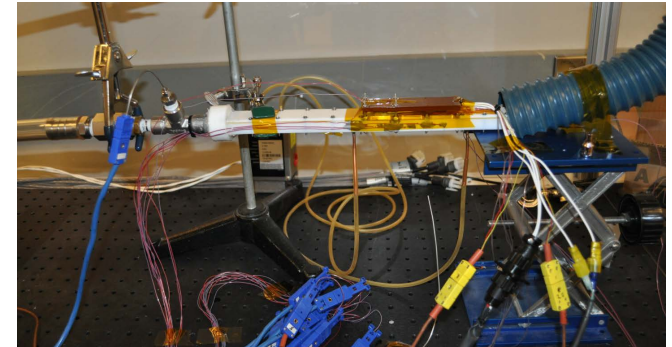


# High Temperature Air-Cooled Inverter

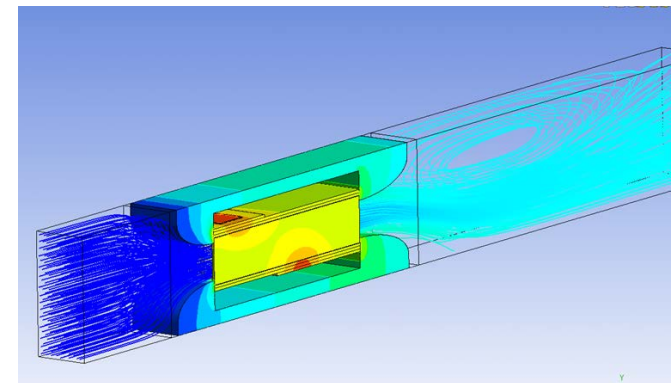


## Thermal Design

Design concept and balance-of-system testing



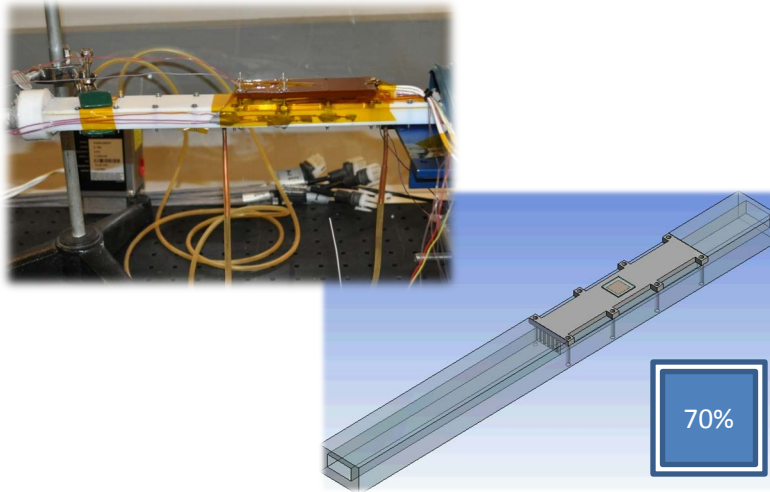
Model validation and design optimization



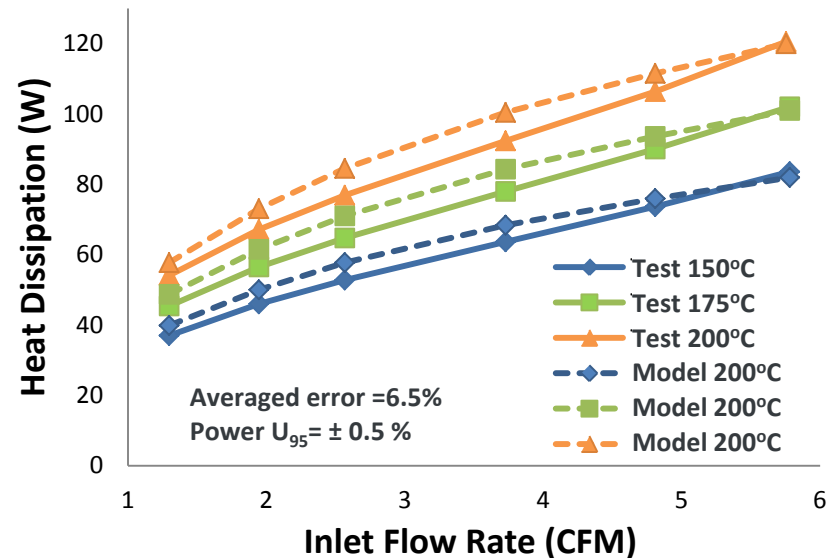
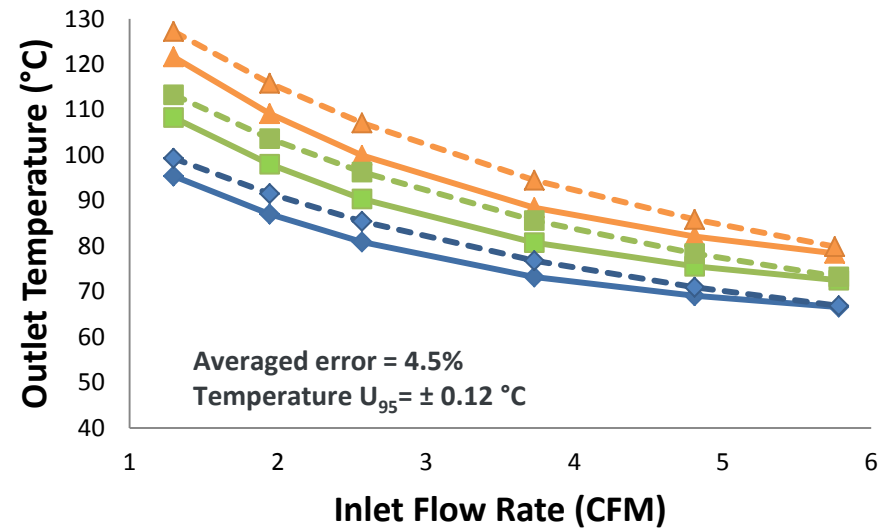
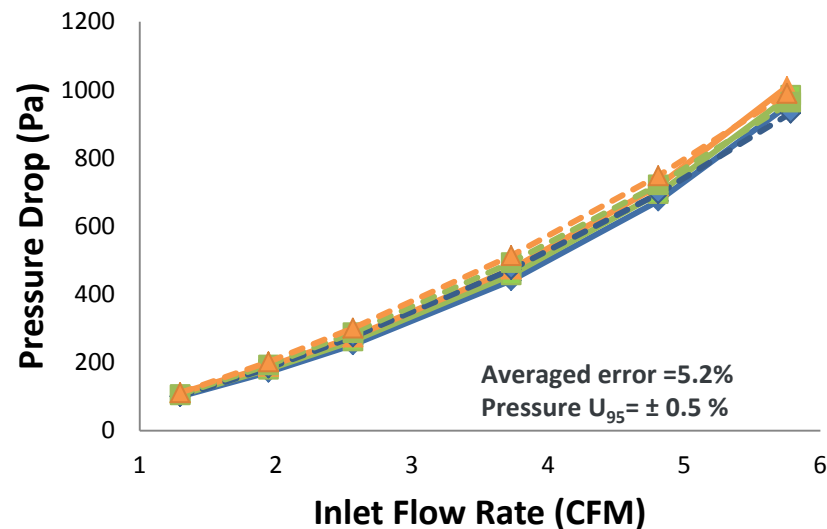
# Model Validation

*Less Than 6.5% error between model and experiment*

FY12/Milestone 1



- Chip temperature: 150°C, 175°C, 200°C
- 5 W/m<sup>2</sup>K heat transfer coefficient at the exterior walls
- 70% thermal contact between device and fin





# Module Design Improvement

## *Sub-module computational fluid dynamics optimization*

### Design Constraints

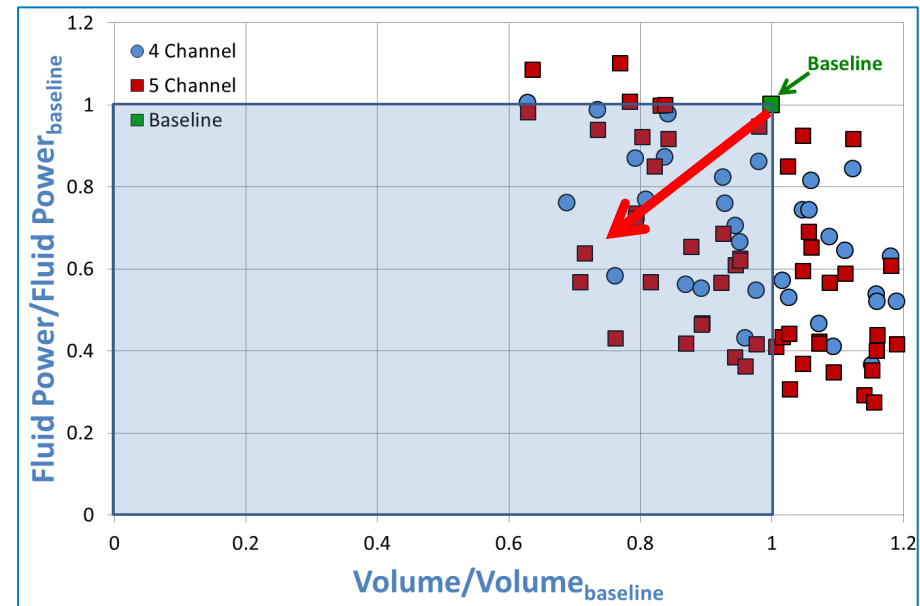
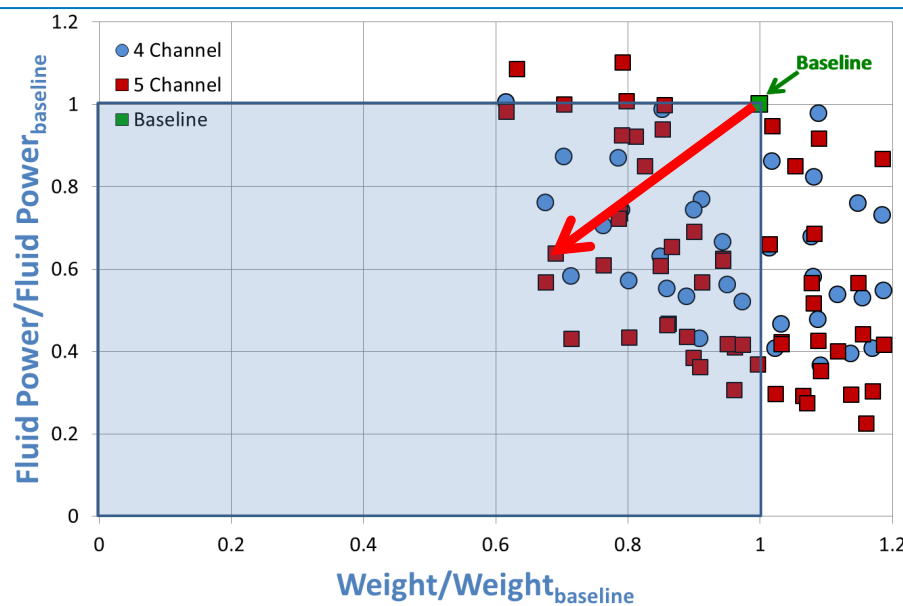
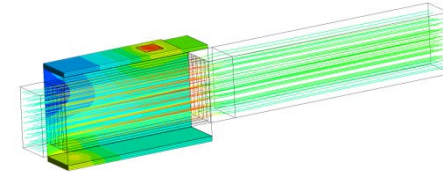
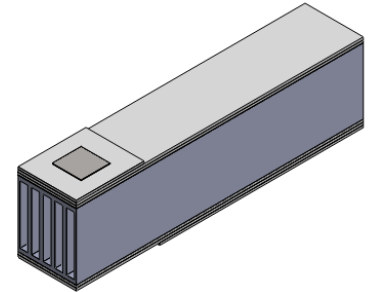
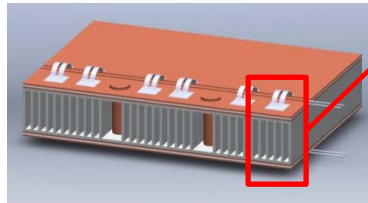
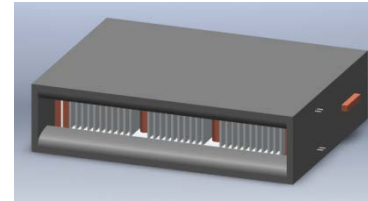
- Heat dissipation
- Device temperature

### Optimization Parameters

- Device location
- Fin thickness
- Channel width
- Base plate thickness
- Fin height
- Fin length

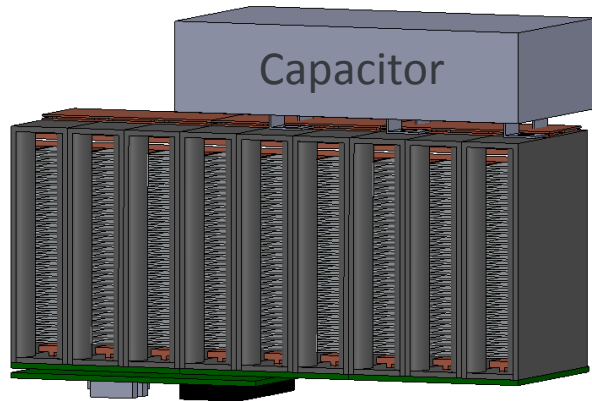


Fluid  
Power

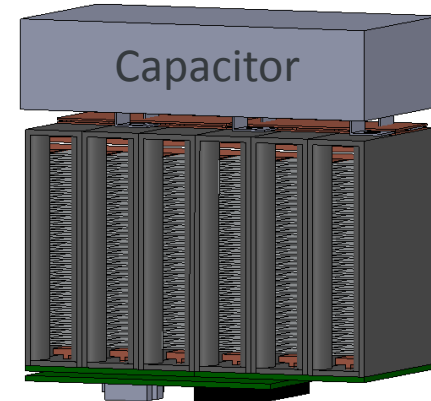


# Balance-of-Inverter Assumptions

*Impacts volume, weight, and electrical power*



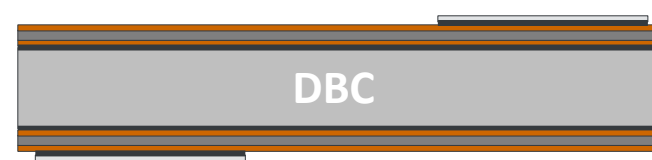
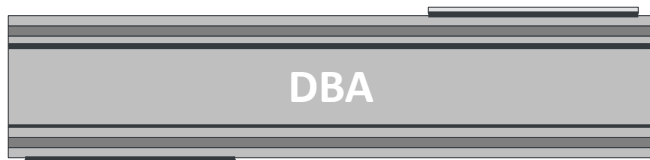
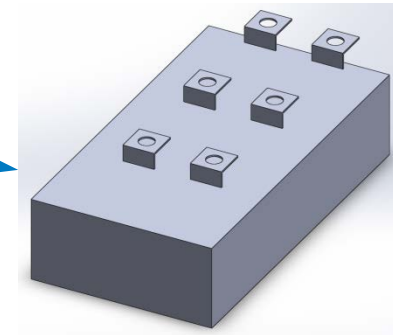
9 modules



6 modules

- 55 kW electrical power assumed
- 25 W per device heat dissipation (2.7 kW)
- 55 kW electrical power assumed
- 45 W per device heat dissipation (3.2 kW)

- Casing volume adjusted for fin geometry
- Capacitor  $\sim 1.13 \text{ L}^1$ ,  $\sim 1.35 \text{ kg}^*$
- Gate driver + control board  $\sim 0.88 \text{ L}^*$ ,  $\sim 0.34 \text{ kg}^{**}$
- Direct-bond copper (DBC) and Direct-bond aluminum (DBA)

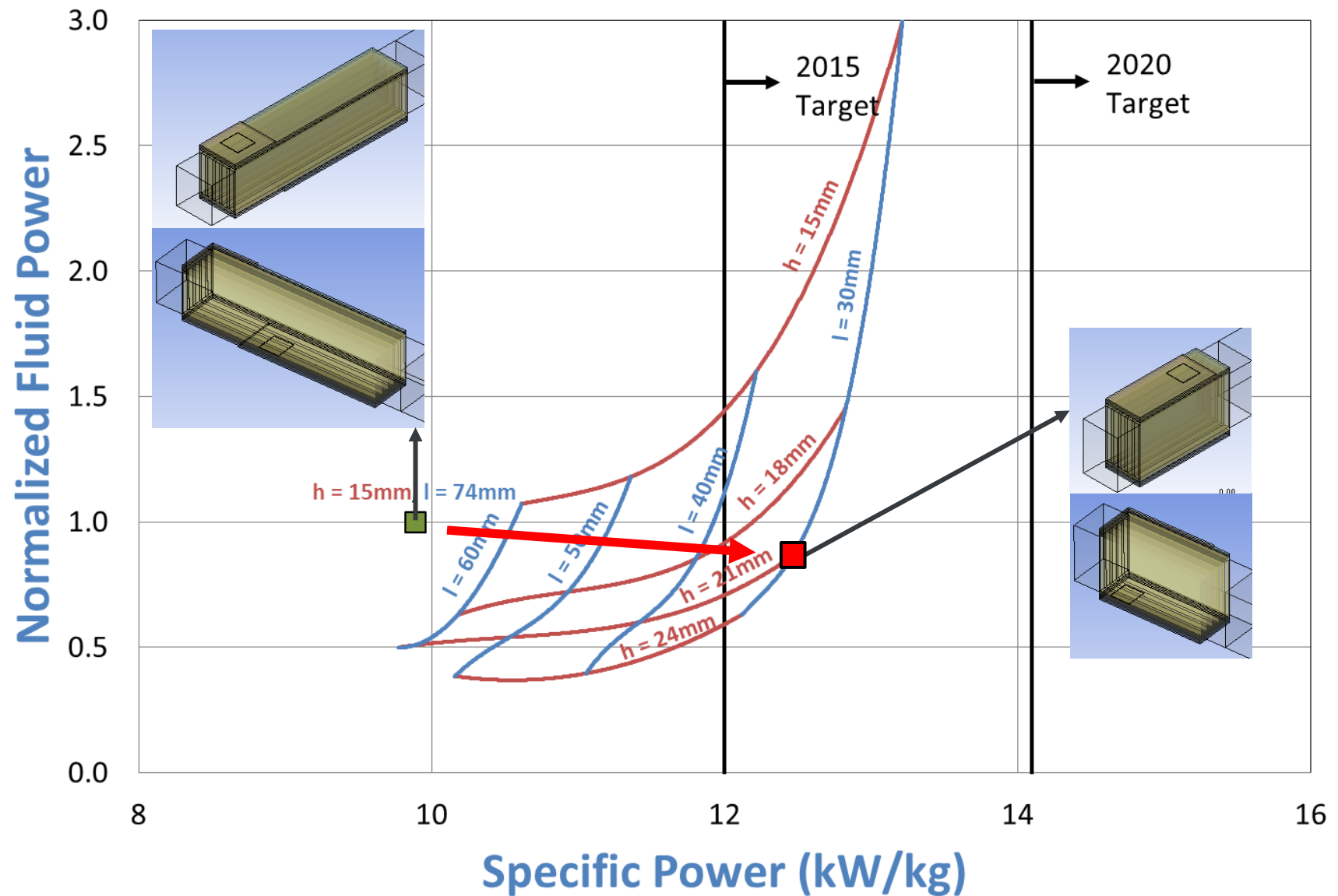


\*: Assumption provided by ORNL, \*\*: NREL assumption based on similar device measurement

# Optimized Geometries Improve Specific Power

*On track to meet DOE 2015 technical target*

FY13 – Go/No-Go 1

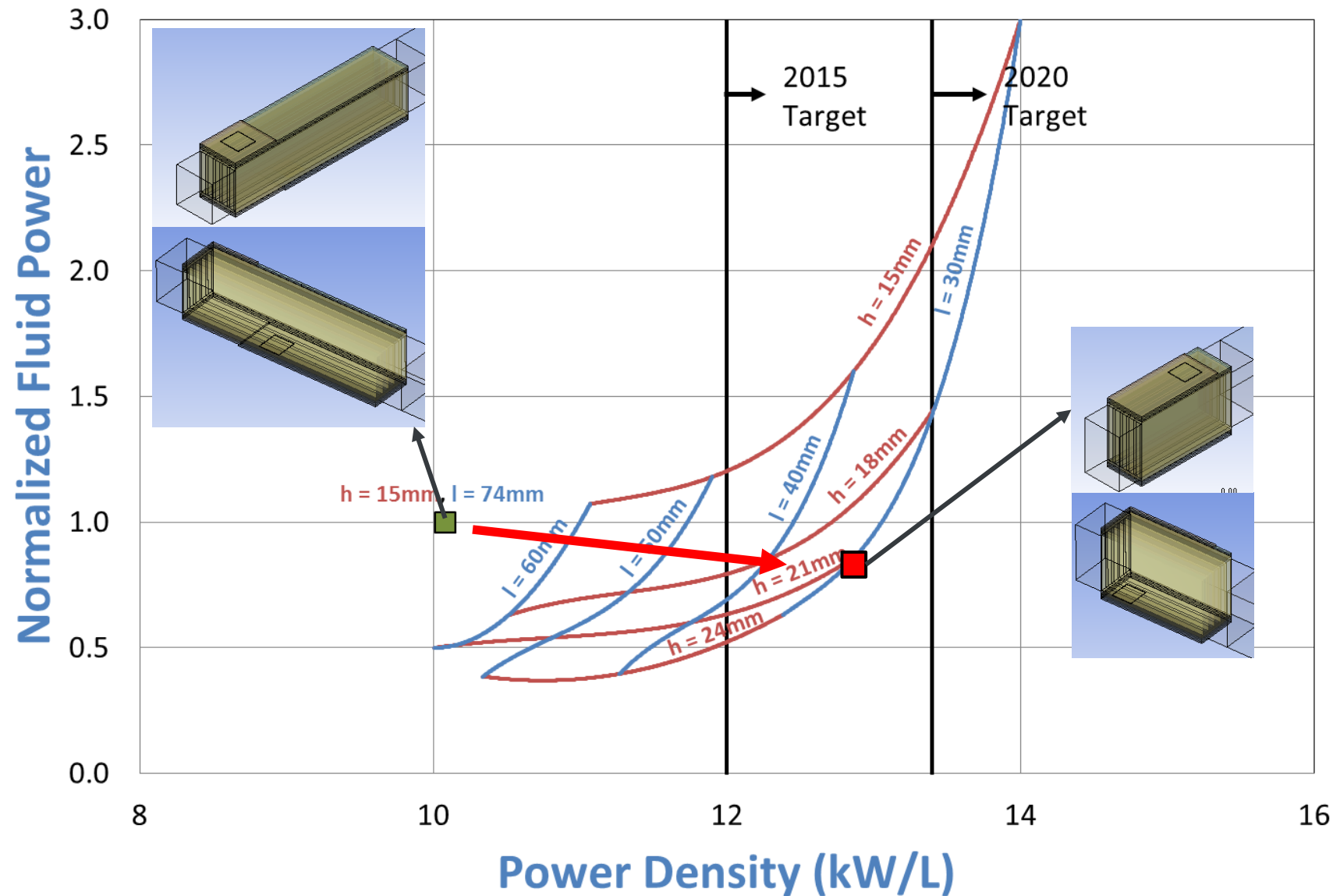


9 module, DBC

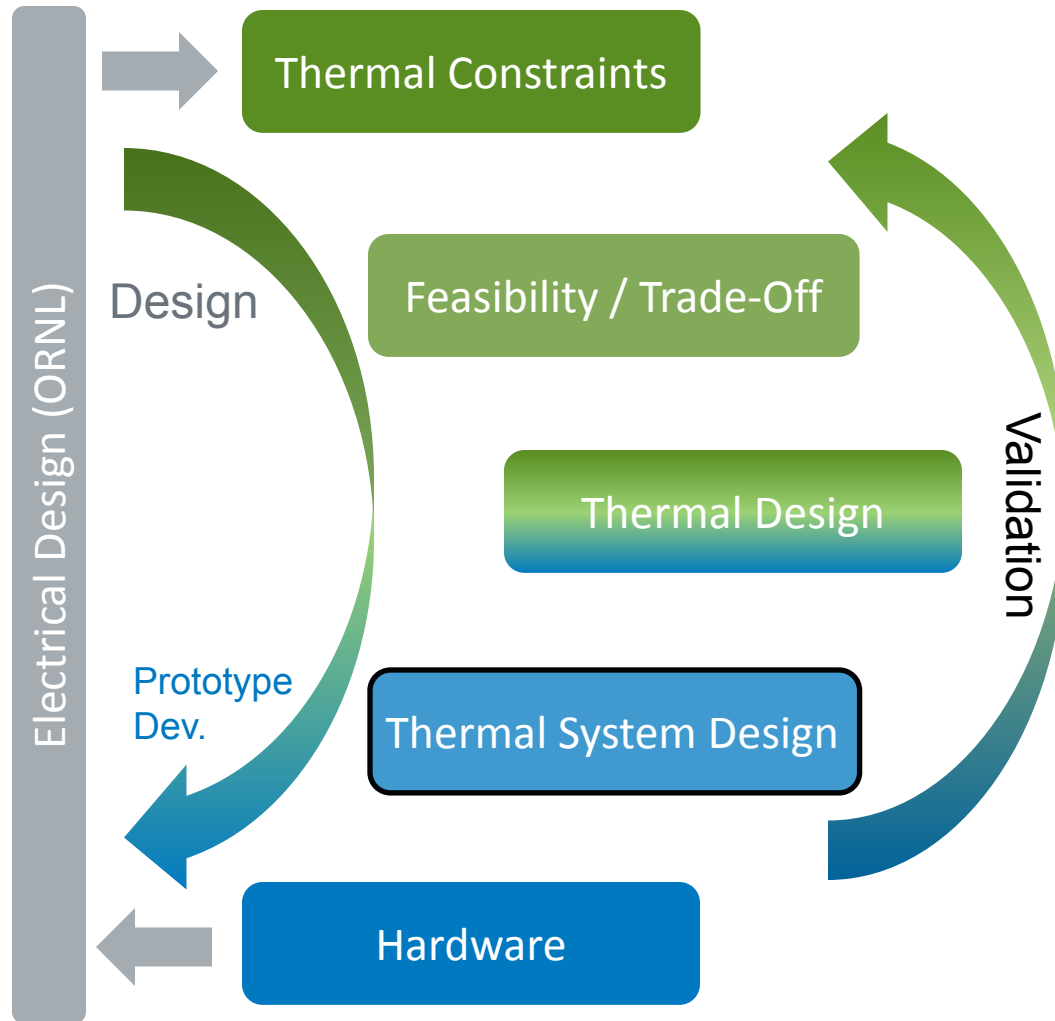
# Optimized Geometries Improve Power Density

*On track to meet DOE 2015 technical target*

FY13 – Go/No-Go 1

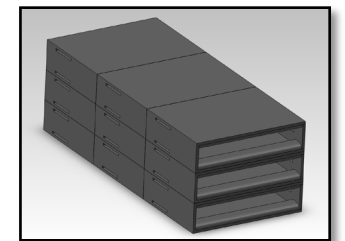
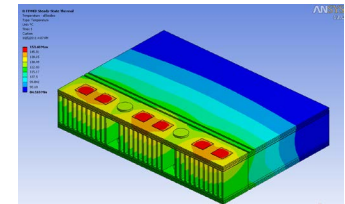
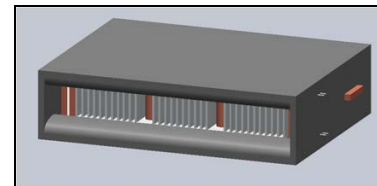


9 module, DBC

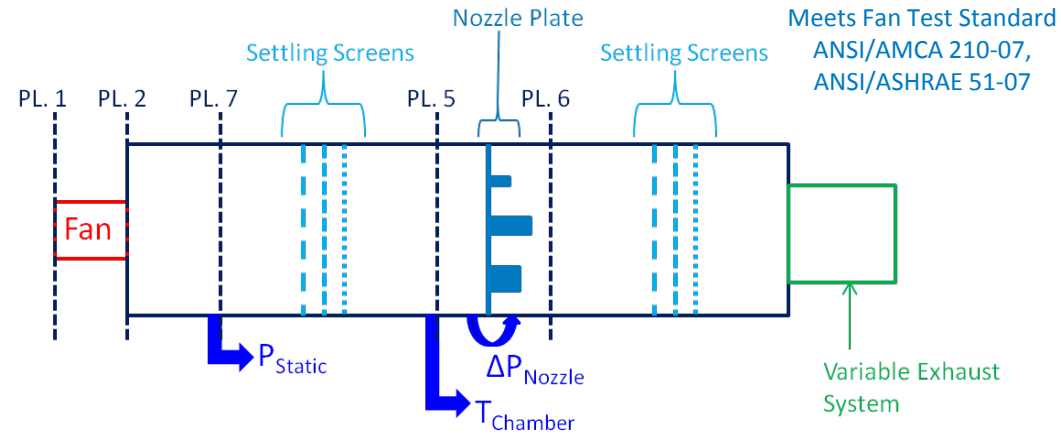


## Thermal System Design

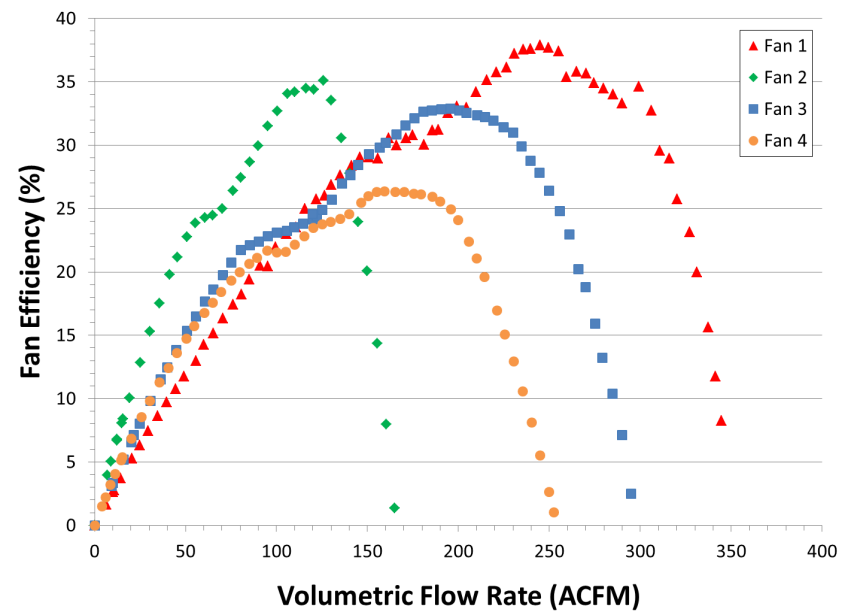
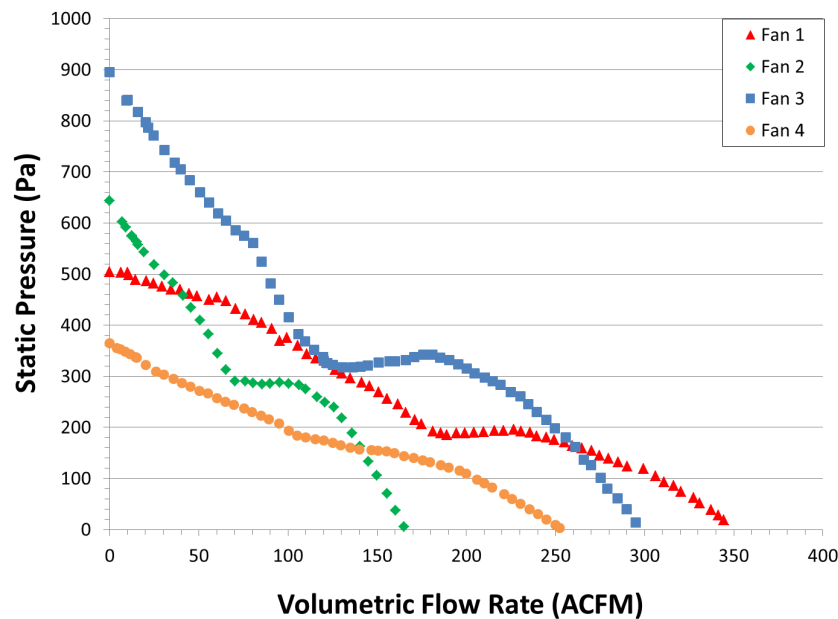
- **Balance-of-system design**
- **Couple module model to balance-of-system test results**
- **Full system level models**
- **Design drawings to build thermal management prototype**



# System-Level Test Bench



- Range: 5–500 CFM
- U-95 Flow:  $\pm 1.5$  CFM, U-95 Pressure:  $\pm 1.6$  Pa

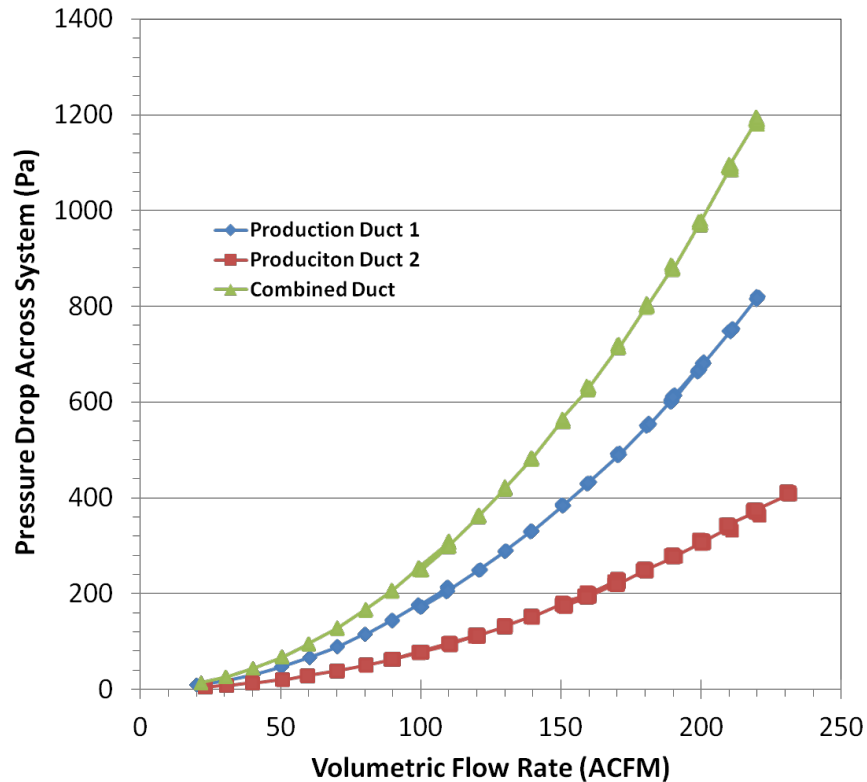




# Balance of System: Ducting Design

## Pressure loss and location options

Example Production Vehicle Air Ducts



Production Duct 1



Production Duct 2



Inverter Location

*Volkswagen Touareg*

*Toyota Highlander*

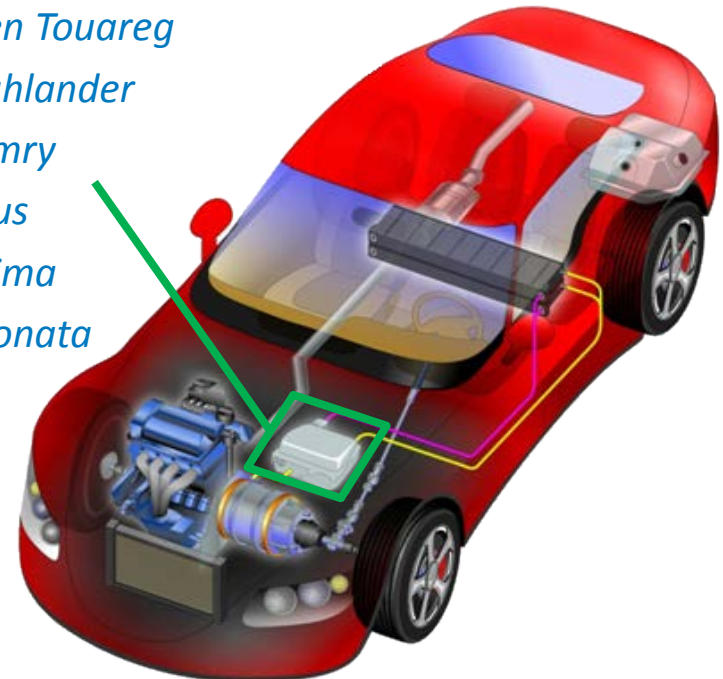
*Toyota Camry*

*Toyota Prius*

*Nissan Altima*

*Hyundai Sonata*

*Chevy Volt*

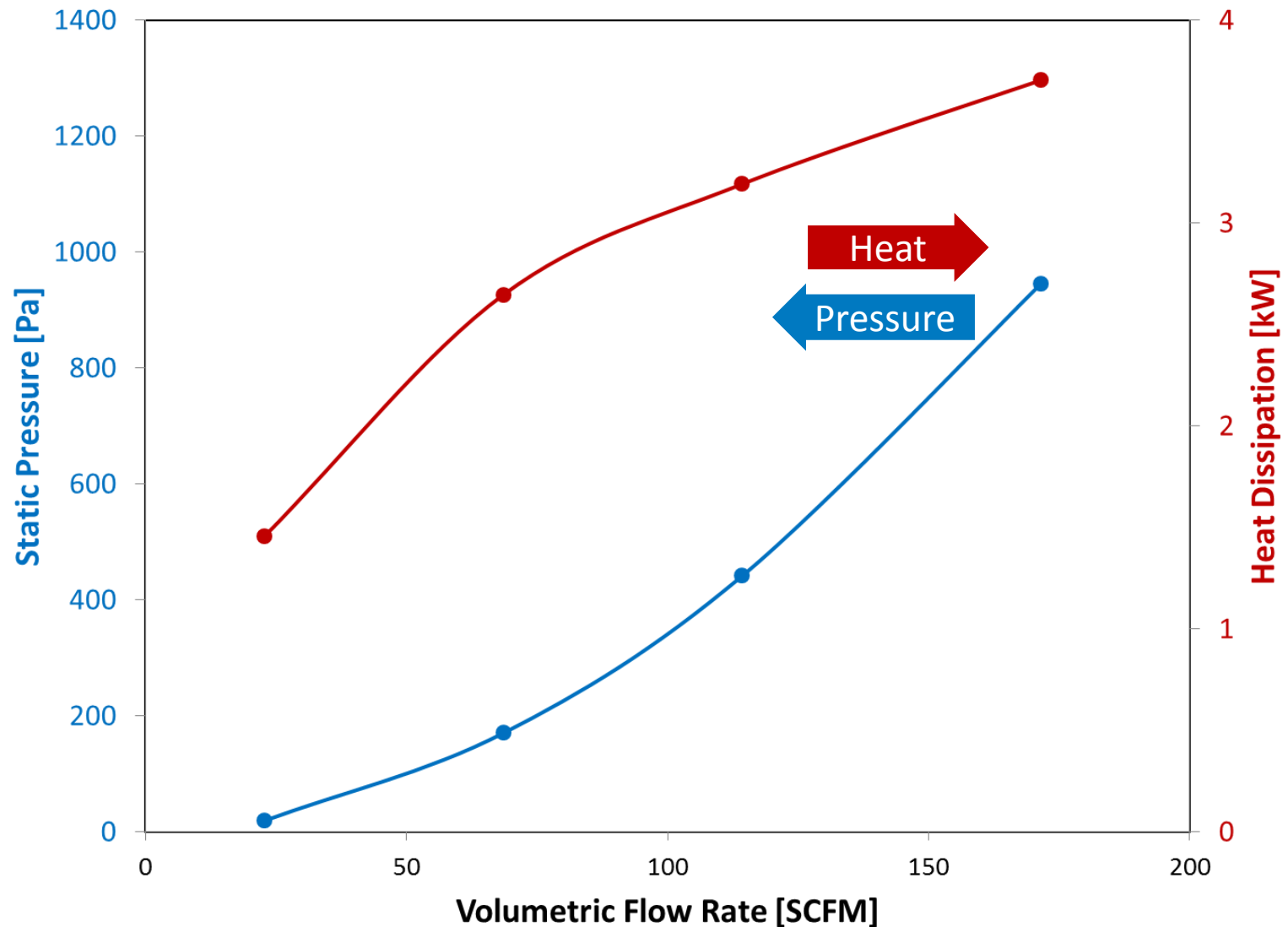


[1]



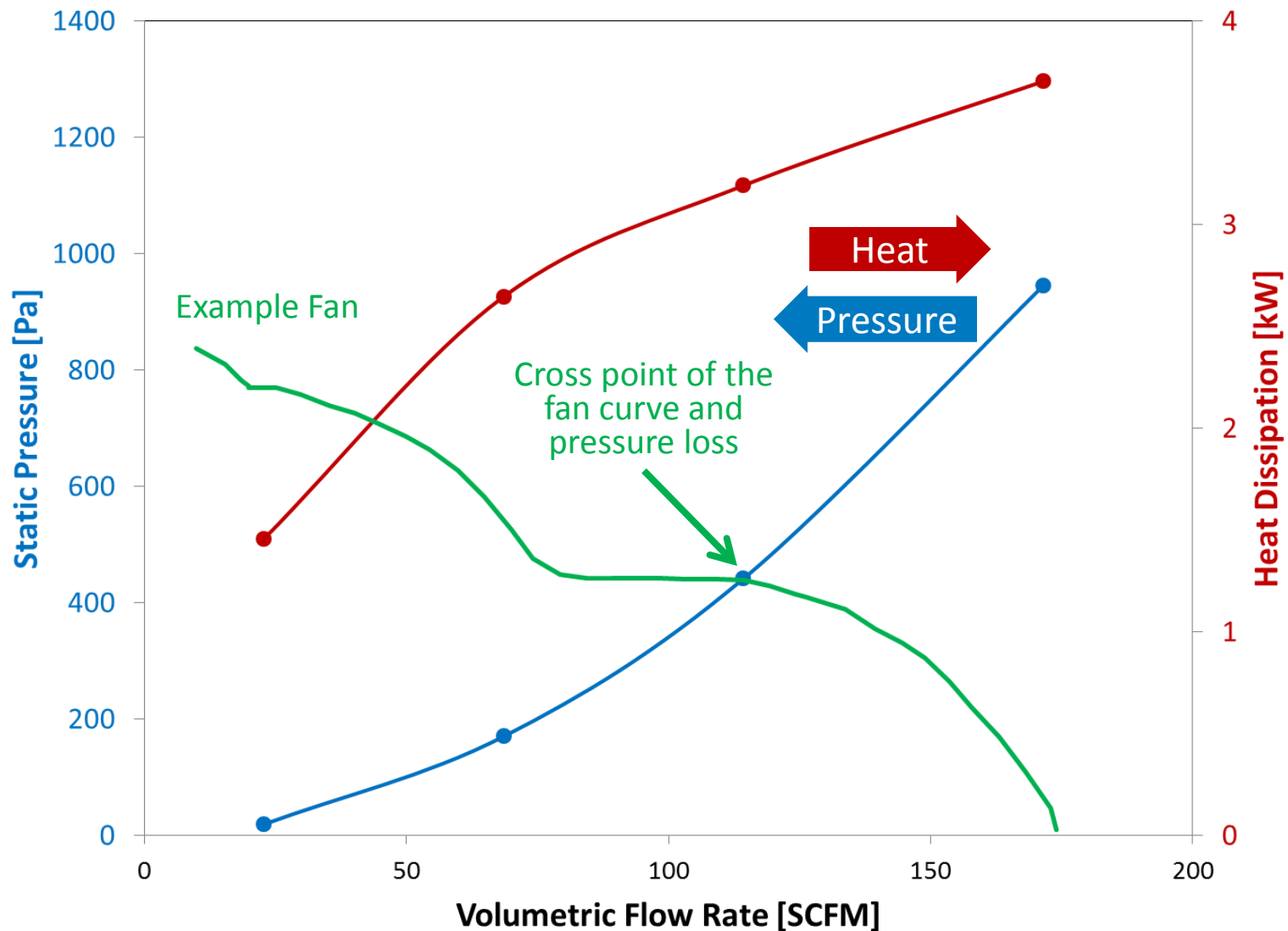
# Example System Flow Study

*9-by-1 array design, DBC, and 175°C*



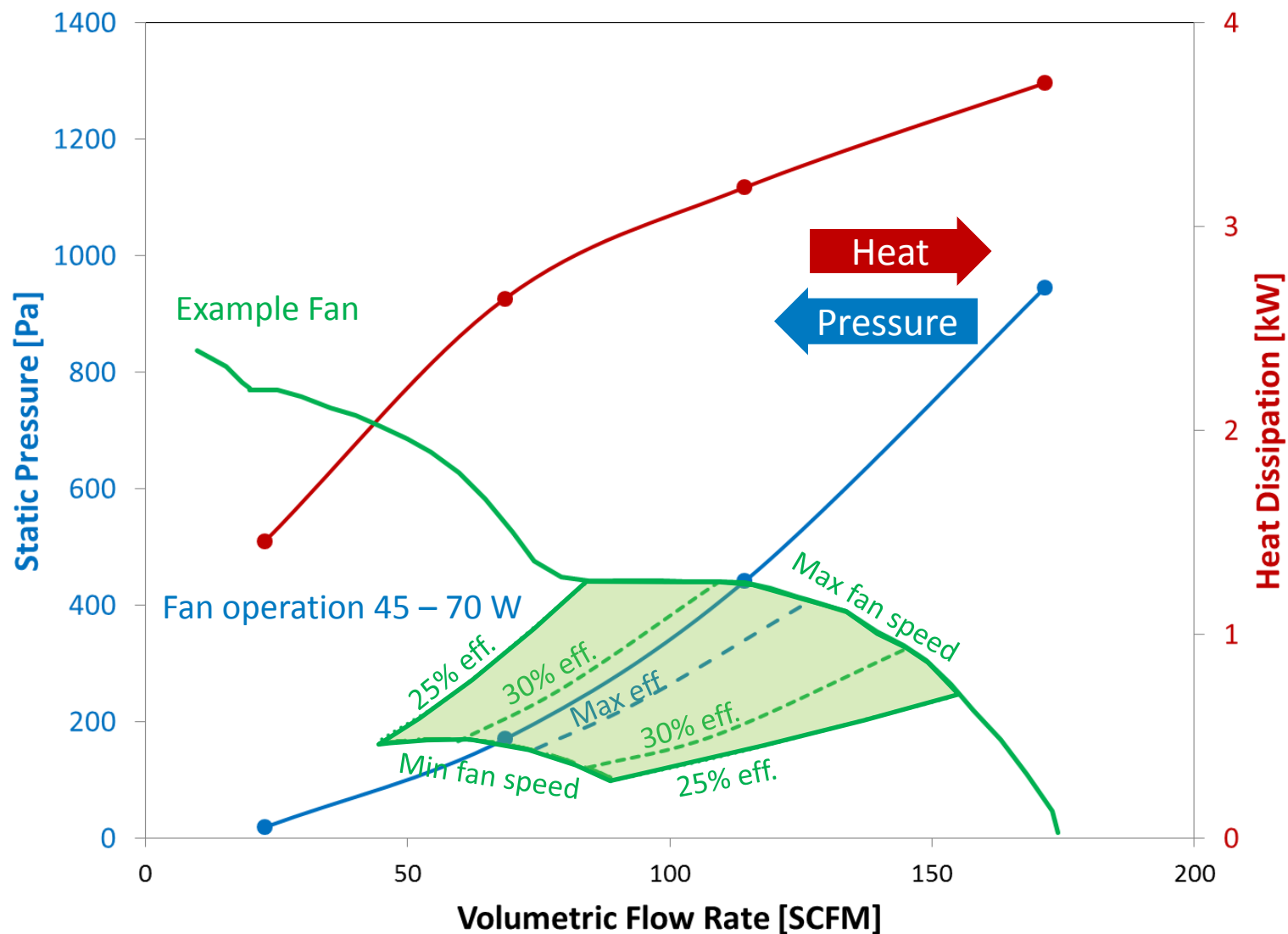
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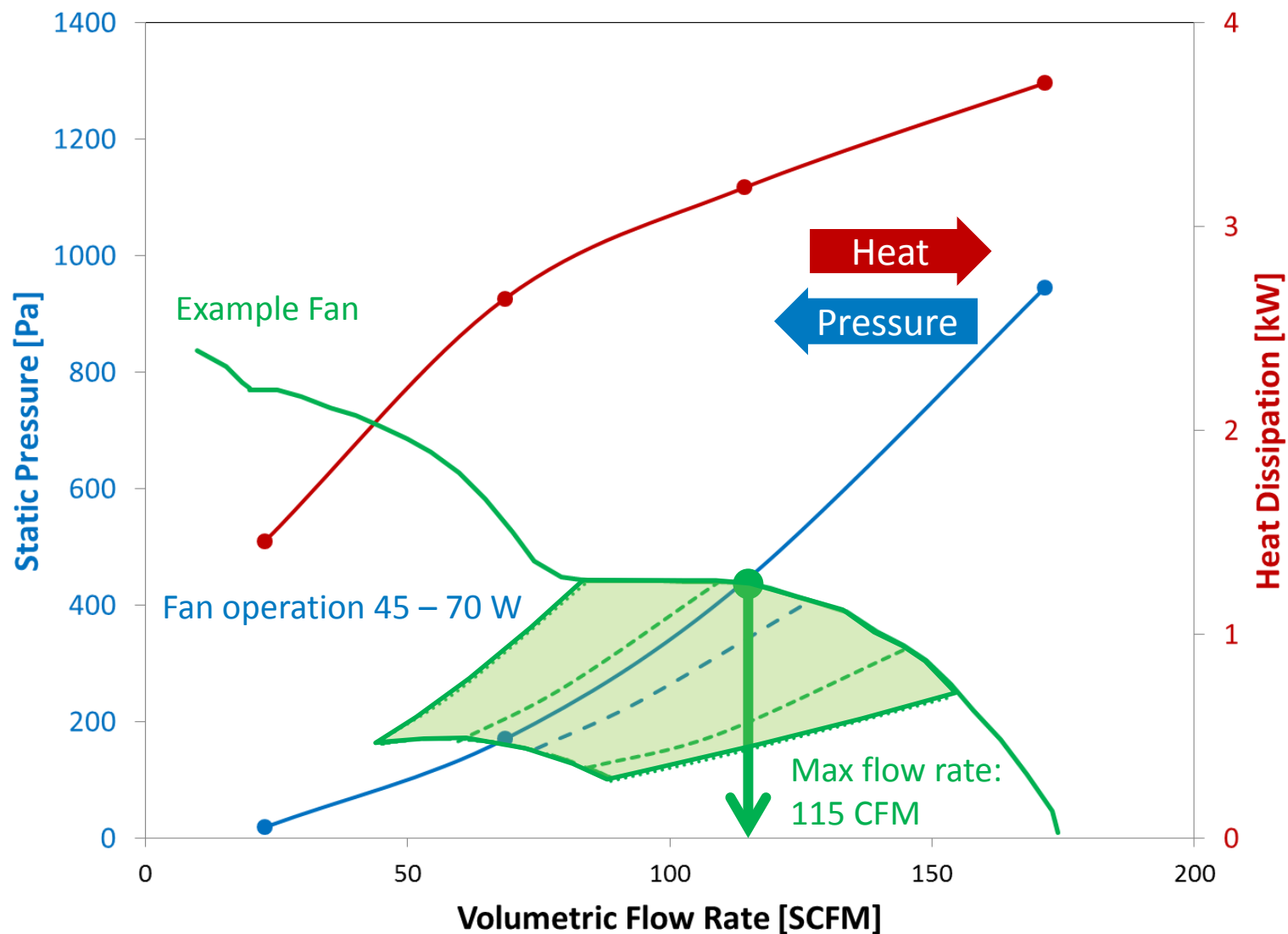
# Example System Flow Study

*9-by-1 array design, DBC, and 175°C*



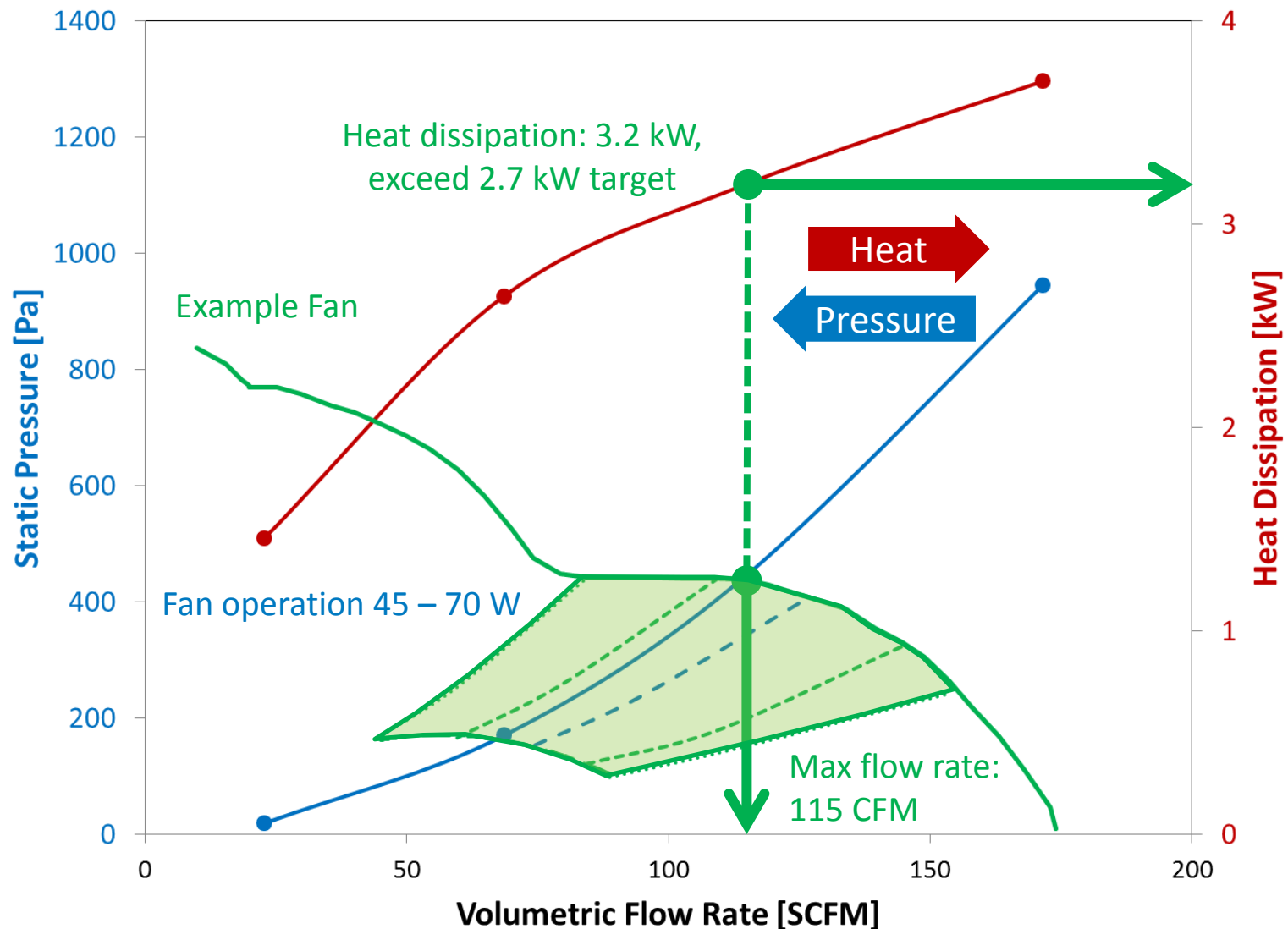
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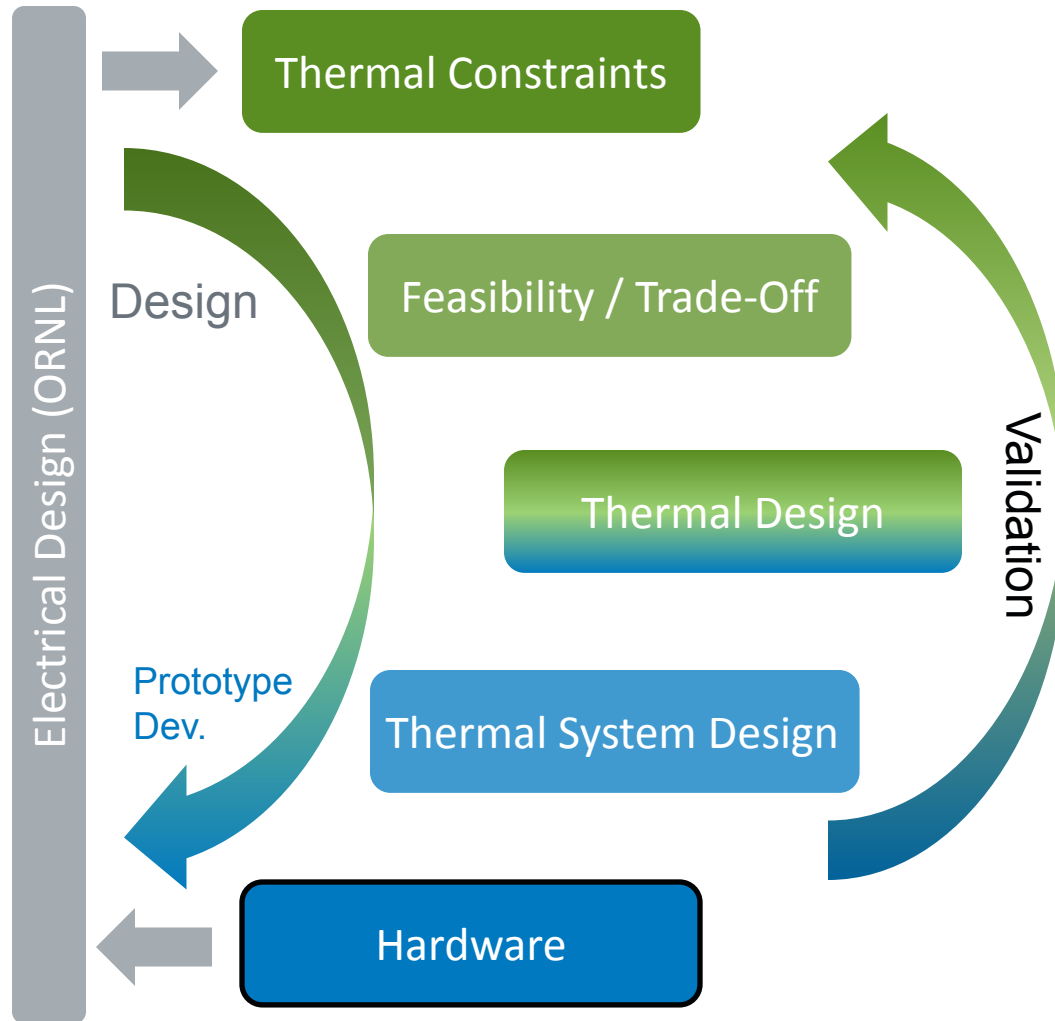
*9-by-1 array design, DBC, and 175°C*



# Example System Flow Study

*9-by-1 array design, DBC, and 175°C*





## Hardware

- Build prototype thermal management system and test on bench
- Use results to feed back and improve design
- Determine progress toward 2015 goals



# Future Work

- FY13
  - Validate sub-module model results
  - Build and test air-cooled module-level thermal management system.
  - Test balance-of-system proof of concept
  - Projected Go/No-Go Decision Point: If projected results meet the DOE inverter target for volume and weight, pursue module build
- FY14
  - Work with ORNL to build and test lower power high temperature air-cooled inverter system (one SiC module by 4/14)
  - Build and demonstrate full system thermal management system
  - Projected Go/No-Go Decision Point: If test results are on track to meet DOE inverter targets for volume and weight, pursue full inverter build
- FY15
  - NREL to finalize and prototype inverter thermal management system
  - ORNL to finalize and prototype inverter electrical system
  - NREL and ORNL demonstrate full inverter operation, quantifying performance
  - Projected Go/No-Go Decision Point: If test results meet DOE 2015 inverter targets for volume and weight, then pursue full vehicle-level demonstration with industry partners



# Summary

DOE

Mission

Support

- Overcome barriers to adoption of low-cost air-cooled heat exchangers for power electronics; air remains the ultimate sink.

Approach

- Create system-level understanding and designs addressing advanced cooling technology, balance of system, and package thermal interactions; develop solutions from fundamental heat transfer, then system level design, to application – culminating in vehicle-level viability demonstration with research partners.

# Summary

## Technical Accomplishments

- Optimized thermal design showing improvements in weight, volume, and power density can help meet DOE technical targets
- Showed through computational fluid dynamics modeling that the high temperature air-cooled inverter is on track to meet DOE 2015 specific weight and power density targets
- Tested production balance-of-system components and showed feasibility, now researching design options

## Collaborations

- Strengthened collaboration with ORNL for collaborative high-temperature air-cooled inverter project
- Researching advanced air-cooling technology in collaboration with Sapa, GE, and Momenive
- Working on adding a fan manufacturer collaboration

# Acknowledgments and Contact

## Acknowledgments:

- Susan Rogers and Steven Boyd  
*U.S. Department of Energy*
- Madhu Sudhan Chinthavali &  
Andrew Wereszczak  
*Oak Ridge National Laboratory*

## Team Members:

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Kevin Bennion  
Charlie King  
Casey Smith

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Phone: (303)-275-4062



# References

## Slide 2

1. Honda Insight photograph: John P. Rugh, NREL
2. Honda power electronics photograph: Oak Ridge National Laboratory
3. Electric Mini Cooper photograph: DOE Advanced Vehicle Testing Activity & Idaho National Laboratory
4. AC Propulsion AC-150 photograph: Jason A. Lustbader & Dean Armstrong, NREL

## Slide 5

1. Device Level Test Bench: Xin He, NREL
2. System Test Bench: Casey Smith, NREL

## Slide 22

1. Test bench photograph: Casey Smith, NREL

## Slide 28

1. Duct photographs: Casey Smith, NREL

## Slide 32

1. NREL photographs: Dennis Schroeder, NREL Image Gallery 19050